

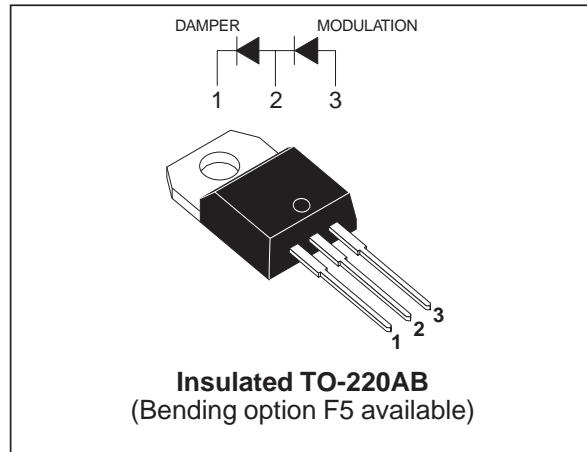
## DAMPER + MODULATION DIODE FOR VIDEO

### MAIN PRODUCT CHARACTERISTICS

	MODUL	DAMPER
I <sub>F(AV)</sub>	3 A	6 A
V <sub>RRM</sub>	600 V	1500 V
T <sub>rr</sub> (max)	50 ns	135 ns
V <sub>F</sub> (max)	1.4 V	1.65 V

### FEATURES AND BENEFITS

- Full kit in one package
- High breakdown voltage capability
- Very fast recovery diode
- Specified turn on switching characteristics
- Low static and peak forward voltage drop for low dissipation
- Insulated version:  
Insulated voltage = 2500 V<sub>RMS</sub>  
Capacitance = 7 pF
- Planar technology allowing high quality and best electrical characteristics
- Outstanding performance of well proven DTV as damper and new Turboswitch2 as modulation



### DESCRIPTION

High voltage semiconductor especially designed for horizontal deflection stage in standard and high resolution video display with E/W correction.

The insulated TO-220AB package includes both the DAMPER diode and the MODULATION diode. Assembled on automated line, it offers excellent insulating and dissipating characteristics, thanks to the internal ceramic insulation layer.

### ABSOLUTE RATINGS (limiting values, per diode)

Symbol	Parameter	Value		Unit
		MODUL	DAMPER	
V <sub>RRM</sub>	Repetitive peak reverse voltage	600	1500	V
I <sub>FSM</sub>	Surge non repetitive forward current tp = 10 ms sinusoidal	35	75	A
T <sub>stg</sub>	Storage temperature range	- 40 to + 150		°C
T <sub>j</sub>	Maximum operating junction temperature	150		

TURBOSWITCH2 is a trademark of STMicroelectronics

## DMV1500M

### THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
R <sub>th(j-c)</sub>	Damper junction to case	4.8	°C/W
R <sub>th(j-c)</sub>	Modulation junction to case	6	
R <sub>th(c)</sub>	Coupling	0.2	

### STATIC ELECTRICAL CHARACTERISTICS OF THE DAMPER DIODES

Symbol	Parameter	Test conditions	Value				Unit	
			T <sub>j</sub> = 25°C		T <sub>j</sub> = 125°C			
			Typ.	Max.	Typ.	Max.		
V <sub>F</sub> *	Forward voltage drop	I <sub>F</sub> = 6 A	1.4	2.2	1.2	1.65	V	
I <sub>R</sub> **	Reverse leakage current	V <sub>R</sub> = 1500V		100	100	1000	µA	

Pulse test : \* tp = 380 µs, δ < 2%

\*\* tp = 5 ms, δ < 2%

To evaluate the maximum conduction losses of the DAMPER diode use the following equations :

$$P = 1.37 \times I_F(AV) + 0.047 \times I_F^2(RMS)$$

### STATIC ELECTRICAL CHARACTERISTICS OF THE MODULATION DIODE

Symbol	Parameter	Test condi-tions	Value				Unit	
			T <sub>j</sub> = 25°C		T <sub>j</sub> = 125°C			
			Typ.	Max.	Typ.	Max.		
V <sub>F</sub> *	Forward voltage drop	I <sub>F</sub> = 3A		1.8	1.1	1.4	V	
I <sub>R</sub> **	Reverse leakage current	V <sub>R</sub> = 600V		20	3	50	µA	

Pulse test : \* tp = 380 µs, δ < 2%

\*\* tp = 5 ms, δ < 2%

To evaluate the maximum conduction losses of the MODULATION diode use the following equations :

$$P = 1.12 \times I_F(AV) + 0.092 \times I_F^2(RMS)$$

### RECOVERY CHARACTERISTICS OF THE DAMPER DIODE

Symbol	Parameter	Test conditions	Value		Unit	
			Typ.	Max.		
t <sub>rr</sub>	Reverse recovery time	I <sub>F</sub> = 100mA I <sub>R</sub> = 100mA I <sub>RR</sub> = 10mA	T <sub>j</sub> = 25°C	750	ns	
t <sub>rr</sub>	Reverse recovery time	I <sub>F</sub> = 1A dI <sub>F</sub> /dt = -50A/µs V <sub>R</sub> = 30V	T <sub>j</sub> = 25°C	110	135	ns

## RECOVERY CHARACTERISTICS OF THE MODULATION DIODE

Symbol	Parameter	Test conditions		Value		Unit
		Typ.	Max.	Typ.	Max.	
$t_{rr}$	Reverse recovery time	$I_F = 100\text{mA}$ $I_R = 100\text{mA}$ $I_{RR} = 10\text{mA}$	$T_j = 25^\circ\text{C}$	110	350	ns
$t_{rr}$	Reverse recovery time	$I_F = 1\text{A}$ $dI_F/dt = -50\text{A}/\mu\text{s}$ $V_R = 30\text{V}$	$T_j = 25^\circ\text{C}$		50	ns

## TURN-ON SWITCHING CHARACTERISTICS OF THE DAMPER DIODE

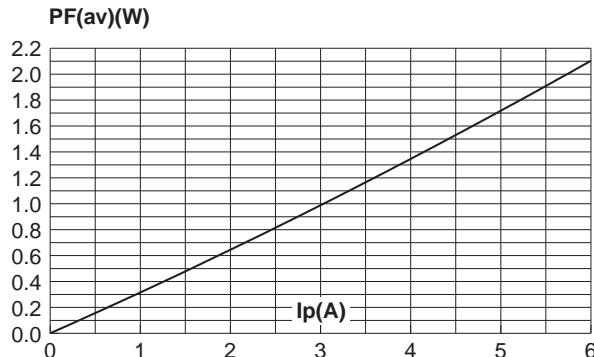
Symbol	Parameter	Test conditions		Value		Unit
		Typ.	Max.	Typ.	Max.	
$t_{fr}$	Forward recovery time	$I_F = 6\text{A}$ $dI_F/dt = 80\text{A}/\mu\text{s}$ $V_{FR} = 3\text{V}$	$T_j = 100^\circ\text{C}$	570		ns
$V_{FP}$	Peak forward voltage	$I_F = 6\text{A}$ $dI_F/dt = 80\text{A}/\mu\text{s}$	$T_j = 100^\circ\text{C}$	21	28	V

## TURN-ON SWITCHING CHARACTERISTICS OF THE MODULATION DIODE

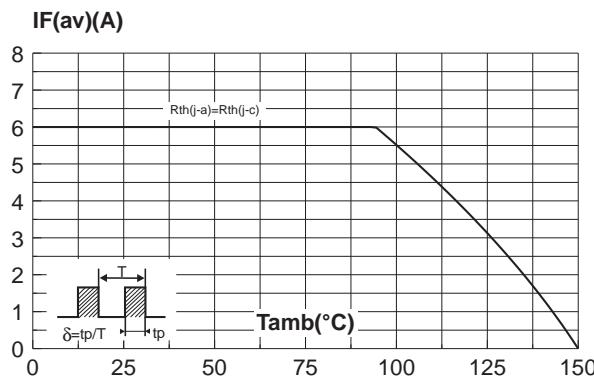
Symbol	Parameter	Test conditions		Value		Unit
		Typ.	Max.	Typ.	Max.	
$t_{fr}$	Forward recovery time	$I_F = 3\text{A}$ $dI_F/dt = 80\text{A}/\mu\text{s}$ $V_{FR} = 2\text{V}$	$T_j = 100^\circ\text{C}$		240	ns
$V_{FP}$	Peak forward voltage	$I_F = 3\text{A}$ $dI_F/dt = 80\text{A}/\mu\text{s}$	$T_j = 100^\circ\text{C}$		8	V

## DMV1500M

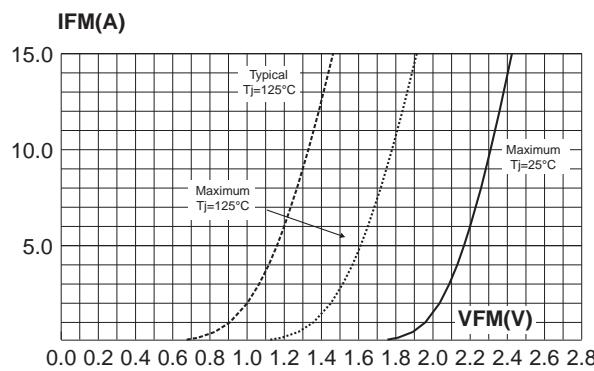
**Fig. 1-1:** Power dissipation versus peak forward current (triangular waveform,  $\delta = 0.45$ ) (damper diode).



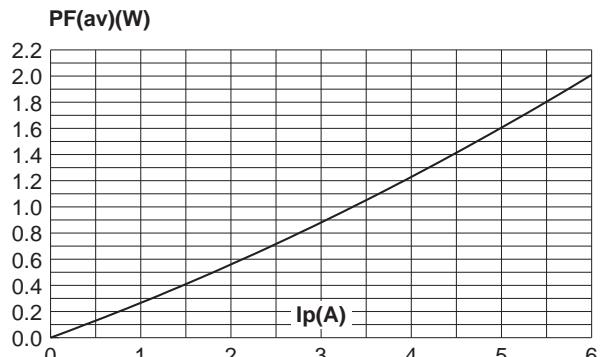
**Fig. 2-1:** Average forward current versus ambient temperature (damper diode).



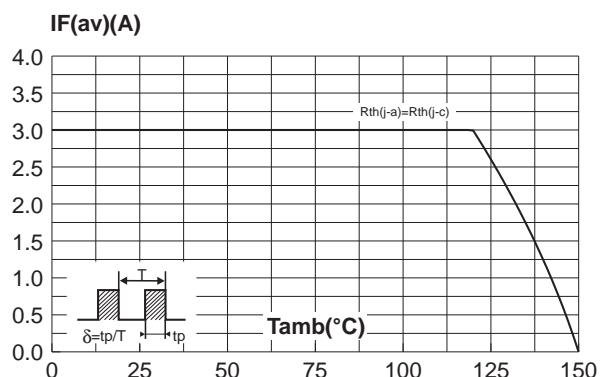
**Fig. 3-1:** Forward voltage drop versus forward current (damper diode).



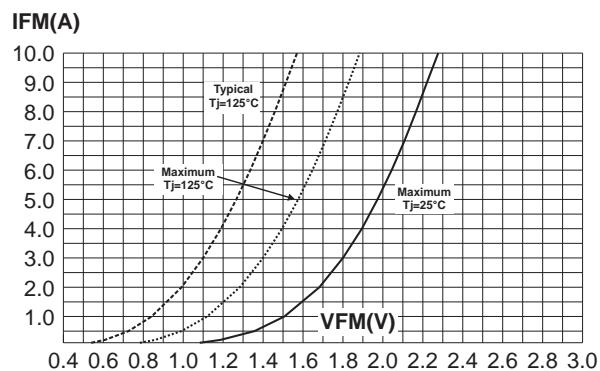
**Fig. 1-2:** Power dissipation versus peak forward current (triangular waveform,  $\delta = 0.45$ ) (modulation diode).



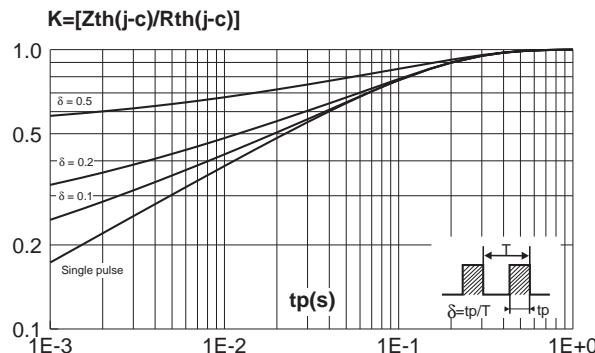
**Fig. 2-2:** Average forward current versus ambient temperature (modulation diode).



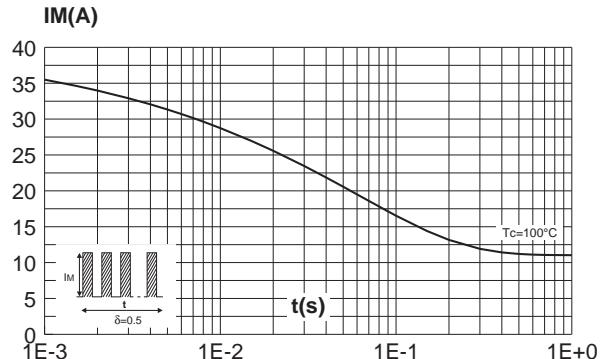
**Fig. 3-2:** Forward voltage drop versus forward current (modulation diode).



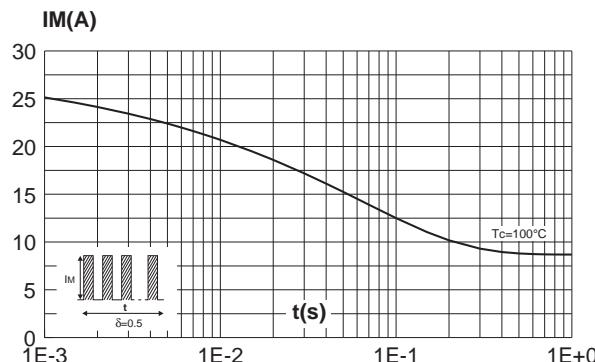
**Fig. 4:** Relative variation of thermal impedance junction to case versus pulse duration.



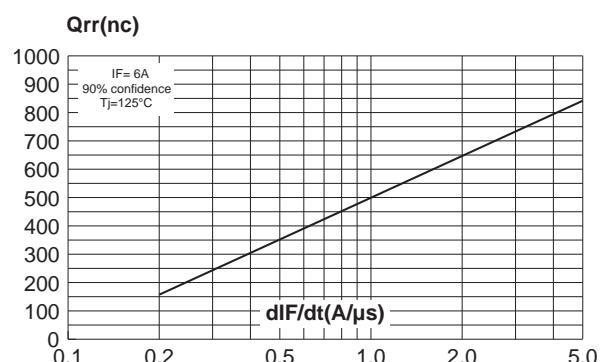
**Fig. 5-1:** Non repetitive surge peak forward current versus overload duration (damper diode).



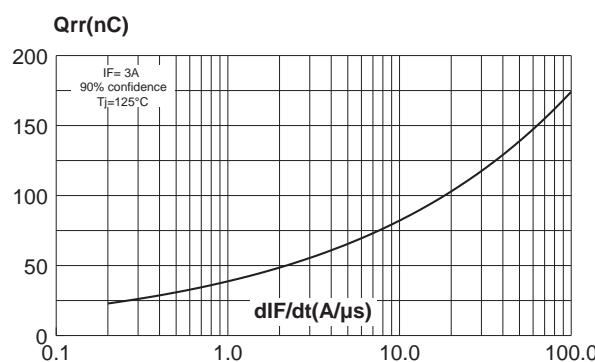
**Fig. 5-2:** Non repetitive surge peak forward current versus overload duration (modulation diode).



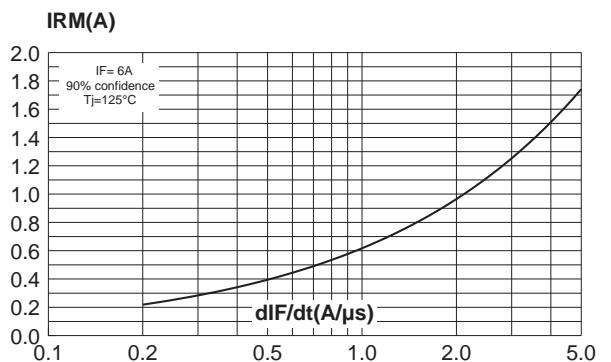
**Fig. 6-1:** Reverse recovery charges versus dIF/dt (damper diode).



**Fig. 6-2:** Reverse recovery charges versus dIF/dt (modulation diode).

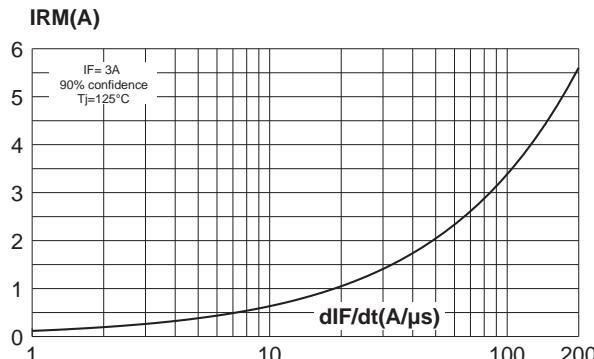


**Fig. 7-1:** Reverse recovery current versus dIF/dt (damper diode).

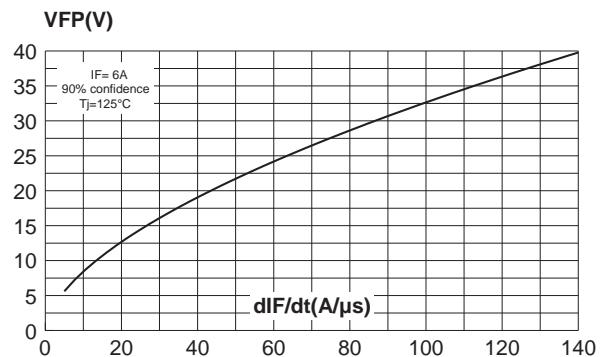


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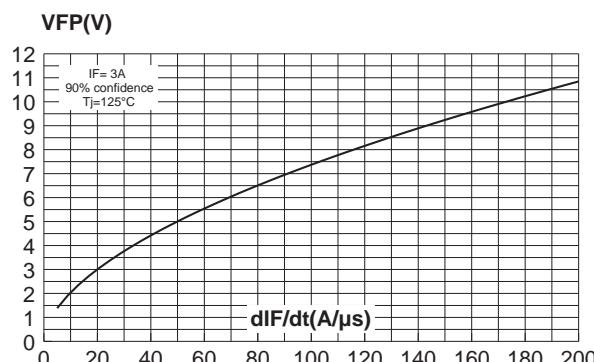
**Fig. 7-2:** Reverse recovery current versus dIF/dt (modulation diode).



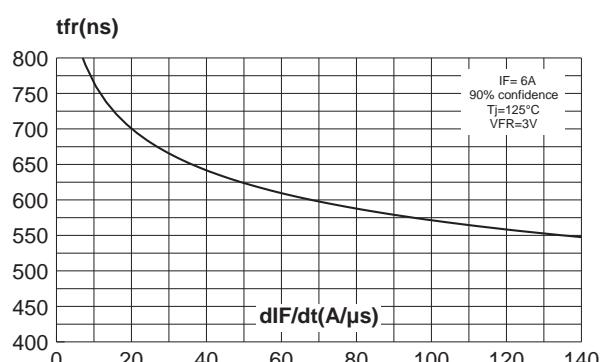
**Fig. 8-1:** Transient peak forward voltage versus dIF/dt (damper diode).



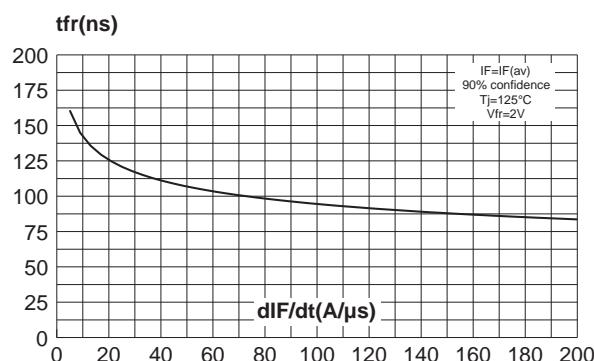
**Fig. 8-2:** Transient peak forward voltage versus dIF/dt (modulation diode).



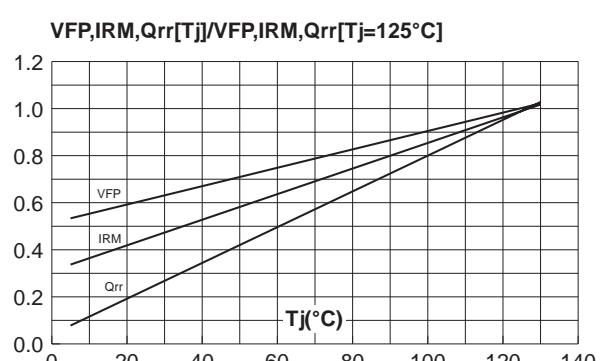
**Fig. 9-1:** Forward recovery time versus dIF/dt (damper diode).



**Fig. 9-2:** Forward recovery time versus dIF/dt (modulation diode).

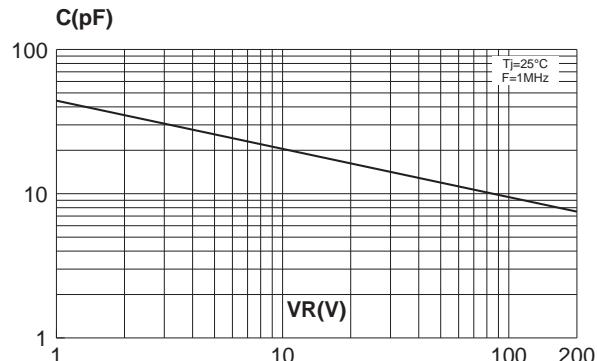


**Fig. 10:** Dynamic parameters versus junction temperature (damper & modulation diodes).

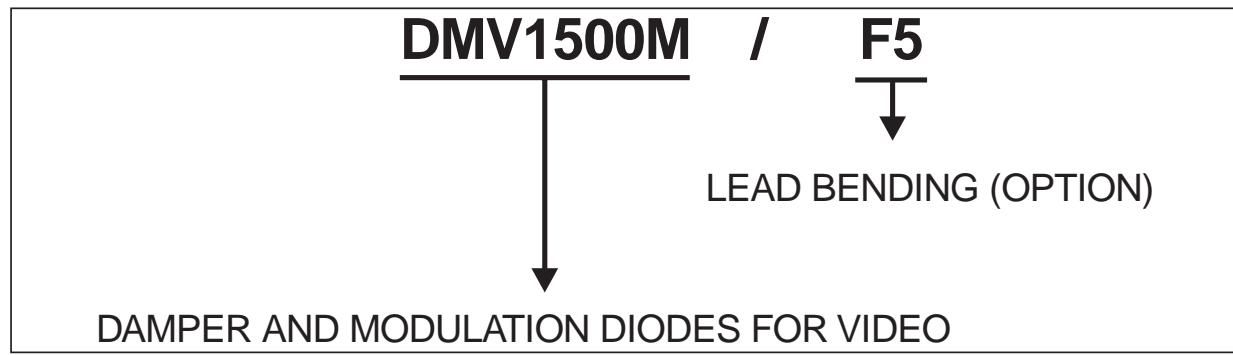


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**Fig. 11:** Junction capacitance versus reverse voltage applied (typical values) (damper & modulation diodes).



## ORDERING INFORMATION

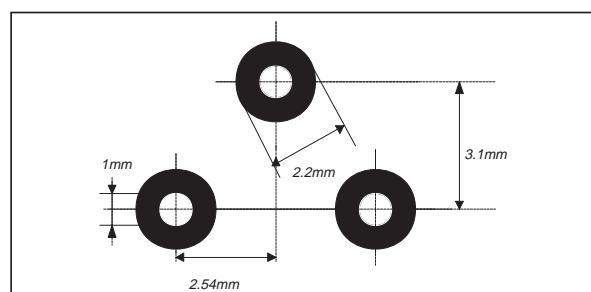


# DMV1500M

## PACKAGE MECHANICAL DATA TO-220AB F5 OPTION

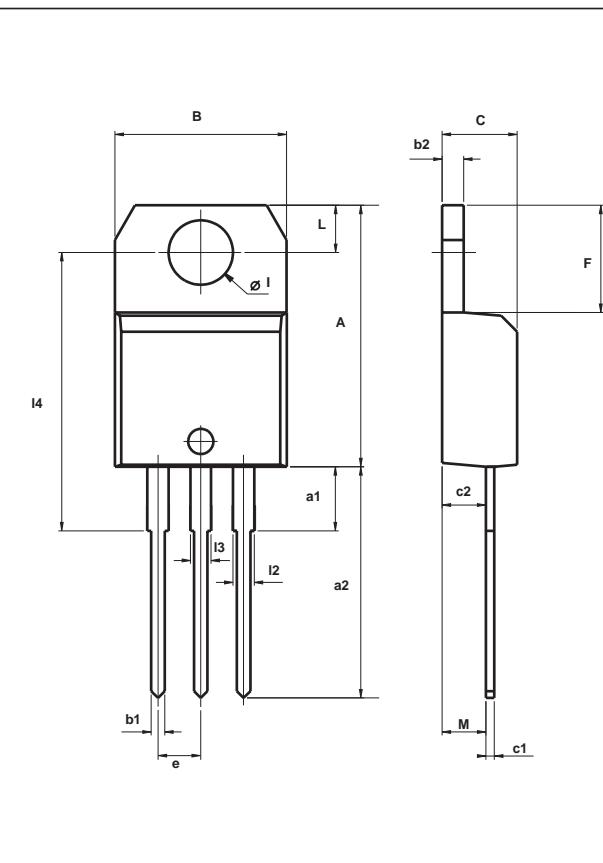
REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	15.20	15.90	0.598	0.625
a1	24.16	26.90	0.951	1.059
a3	1.65	2.41	0.064	0.094
B	10.00	10.40	0.393	0.409
b1	0.61	0.88	0.024	0.034
b2	1.23	1.32	0.048	0.051
C	4.40	4.60	0.173	0.181
c1	0.49	0.70	0.019	0.027
c2	2.40	2.72	0.094	0.107
e	2.40	2.70	0.094	0.106
F	6.20	6.60	0.244	0.259
I	3.75	3.85	0.147	0.151
L	2.65	2.95	0.104	0.116
I2	1.14	1.70	0.044	0.066
I3	1.14	1.70	0.044	0.066
I4	15.80	16.80	0.622	0.661
	16.40 typ.		0.645 typ.	
M1	2.92	3.30	0.114	0.129
R1	1.40 typ.		0.055 typ.	
R2	1.40 typ.		0.055 typ.	

## PRINTED CIRCUIT LAYOUT FOR F5 LAYOUT



- Cooling method: by conduction (c)
- Recommended torque value: 0.8 m.N.
- Maximum torque value: 1 m.N.

**PACKAGE MECHANICAL DATA**  
TO-220AB



REF.	DIMENSIONS					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	15.20		15.90	0.598		0.625
a1		3.75			0.147	
a2	13.00		14.00	0.511		0.551
B	10.00		10.40	0.393		0.409
b1	0.61		0.88	0.024		0.034
b2	1.23		1.32	0.048		0.051
C	4.40		4.60	0.173		0.181
c1	0.49		0.70	0.019		0.027
c2	2.40		2.72	0.094		0.107
e	2.40		2.70	0.094		0.106
F	6.20		6.60	0.244		0.259
I	3.75		3.85	0.147		0.151
I4	15.80	16.40	16.80	0.622	0.646	0.661
L	2.65		2.95	0.104		0.116
I2	1.14		1.70	0.044		0.066
I3	1.14		1.70	0.044		0.066
M		2.60			0.102	

- cooling method: by conduction (c)
- Recommended torque value: 0.8 m.N.
- Maximum torque value: 1 m.N.

Type	Marking	Package	Weight	Base qty	Delivery mode
DMV1500M	DMV1500M	TO-220AB	2.2 g.	50	Tube
DMV1500MF5					

- Epoxy meets UL94, V0

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